ABSTRACT OF THE DISCLOSURE

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A multilayer wiring board is composed of a core portion, a first wiring portion and a second wiring portion. The core portion includes a core insulating layer containing a carbon fiber material. The first wiring portion is bonded to the core portion and has a laminated structure including at least a first insulating layer and a first wiring pattern, the first insulating layer containing glass cloth. The second wiring portion is bonded to the first wiring portion and has a laminated structure including at least a second insulating layer and a second wiring pattern. The core portion, the first wiring portion and the second wiring portion are arranged in a stack.

20 (Fig. 1)